

Application No. 09/841,255

AMENDMENT OF THE CLAIMS

A detailed listing of all claims that are, or were, in the present application, irrespective of whether the claim(s) remains under examination in the application are presented below. The claims are presented in ascending order and each includes one status identifier. Those claims not cancelled or withdrawn but amended by the current amendment utilize the following notations for amendment: 1. deleted matter is shown by strikethrough for six or more characters and double brackets for five or less characters; and 2. added matter is shown by underlining.

1. (Currently Amended) A polishing composition comprising a dispersion of particles, the particles comprising a non-silicon metal compound and having an average particle diameter from about 5 nm to about 50 nm and a distribution of diameters such that at least about 95 percent of the particles have a diameter greater than about 60 percent of the average diameter and less than about 140 percent of the average diameter, wherein the non-silicon metal compound is selected from the group consisting of Fe_3C , Fe_7C_3 , Fe_2O_3 , Fe_3O_4 , MoS_2 , MoO_2 , WC , WO_2 and WS_2 .
2. (Original) The polishing composition of claim 1 wherein the particles are dispersed in an aqueous solution.
3. (Original) The polishing composition of claim 1 wherein the particles are dispersed in a nonaqueous solution.
4. (Canceled).
5. (Canceled).

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6. (Currently Amended) A method of smoothing a surface comprising the step of polishing the surface with ~~[[the]]~~ a polishing composition ~~of claim 1~~ comprising a dispersion of particles, the particles comprising a non-silicon metal compound and having an average particle diameter from about 5 nm to about 50 nm and a distribution of diameters such that at least about 95 percent of the particles have a diameter greater than about 60 percent of the average diameter and less than about 140 percent of the average diameter.
7. (Original) The method of claim 6 wherein the polishing is performed with a polishing pad.
8. (Currently Amended) The method of claim 6 wherein the polishing is performed with a ~~motorized~~ mechanical polisher.
9. (Original) The polishing composition of claim 1 having a single crystalline phase with a uniformity of at least about 90 percent by weight.
10. (Canceled).
12. (Original) The polishing composition of claim 9 wherein the particles have a single crystalline phase with a uniformity of at least about 95 percent by weight.
13. (Original) The polishing composition of claim 9 wherein the particles have a single crystalline phase with a purity of at least about 99 percent by weight.

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14. (Original) The polishing composition of claim 9 wherein the particles have a single crystalline phase with a purity of at least about 99.9 percent by weight.

15. (Currently Amended) A polishing composition comprising a dispersion of particles, the particles comprising a non-silicon metal compound with an average particle diameter from about 5 nm to about 50 nm, wherein less than about 1 particle in 10^6 has a diameter greater than about five times the average diameter, wherein the non-silicon metal compound is selected from the group consisting of Fe_3C , Fe_7C_3 , Fe_2O_3 , Fe_3O_4 , MoS_2 , MoO_2 , WC , WO_3 and WS_2 .

16-22. (Canceled)

23. (Previously Presented) The polishing composition of claim 15 wherein the particles are dispersed in an aqueous solution.

24. (Previously Presented) The polishing composition of claim 15 wherein the particles are dispersed in a nonaqueous solution.

25. (Currently Amended) A method of smoothing a surface comprising polishing the surface with ~~[[the]]~~ a polishing composition of claim 15 comprising a dispersion of particles, the particles comprising a non-silicon metal compound with an average particle diameter from about 5 nm to about 50 nm, wherein less than about 1 particle in 10^6 has a diameter greater than about five times the average diameter.

26. (Previously Presented) A polishing composition comprising a dispersion of particles, the particles comprising a silicon compound with an average particle diameter from about 5 nm to

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about 45 nm, wherein less than about 1 particle in 10^6 has a diameter greater than about five times the average diameter.

27. (Previously Presented) The polishing composition of claim 26 wherein the particles are dispersed in an aqueous solution.

28. (Previously Presented) The polishing composition of claim 26 wherein the particles are dispersed in a nonaqueous solution.

29. (Previously Presented) The polishing composition of claim 26 wherein the silicon compound is selected from the group consisting of SiO_2 and SiC .

30. (Previously Presented) The polishing composition of claim 26 having a single crystalline phase with a uniformity of at least about 90 percent by weight.

31. (Previously Presented) A method of smoothing a surface comprising the step of polishing the surface with the polishing composition of claim 26.